

**400V PNP HIGH VOLTAGE SWITCHING TRANSISTOR IN SOT89**

**Features**

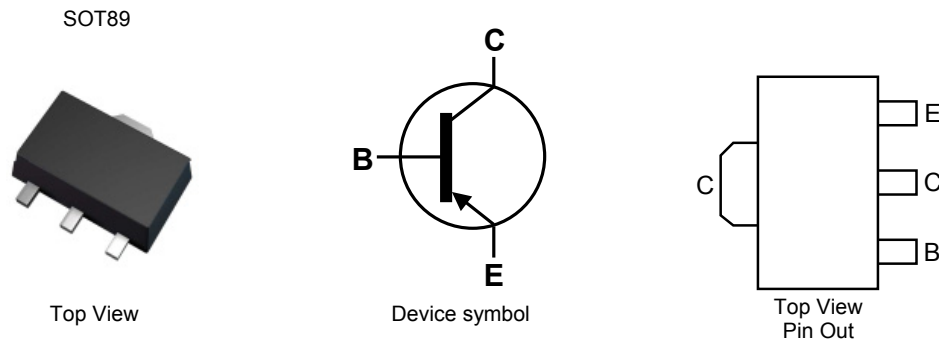
- $BV_{CEO} > -400V$
- $I_C = -0.5A$  Continuous Collector Current
- $I_{CM} = 1A$  Peak Pulse Current
- High Gain Holds up  $h_{FE} \geq 140 @ I_C = -100mA$
- **Totally Lead-Free & Fully RoHS compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 Standards for High Reliability**

**Mechanical Data**

- Case: SOT89
- Case material: molded plastic. "Green" molding compound. UL Flammability Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish - Matte Tin Plated Leads. Solderable per MIL-STD-202, Method 208 Ⓔ③
- Weight: 0.05 grams (Approximate)

**Applications**

- High Voltage Switching

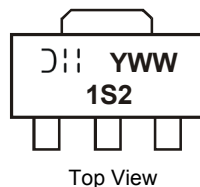


**Ordering Information** (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
2DA1971-7	1S2	7	12	1,000
2DA1971-13	1S2	13	12	2,500

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
  2. See [http://www.diodes.com/quality/lead\\_free.html](http://www.diodes.com/quality/lead_free.html) for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
  3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
  4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

**Marking Information**



1S2 = Product Type Marking Code  
 YWW = Date Code Marking  
 Y = Last digit of year (ex: 1 = 2011)  
 WW = Week code (01 – 53)

### Absolute Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	-400	V
Collector-Emitter Voltage	V <sub>CEO</sub>	-400	V
Emitter-Base Voltage	V <sub>EBO</sub>	-7	V
Continuous Collector Current	I <sub>C</sub>	-0.5	A
Peak Pulse Current	I <sub>CM</sub>	-1	A
Base Current	I <sub>B</sub>	-250	mA

### Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

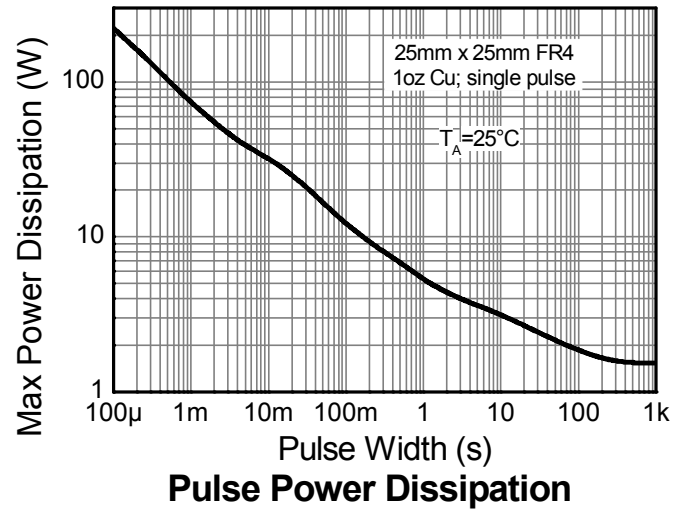
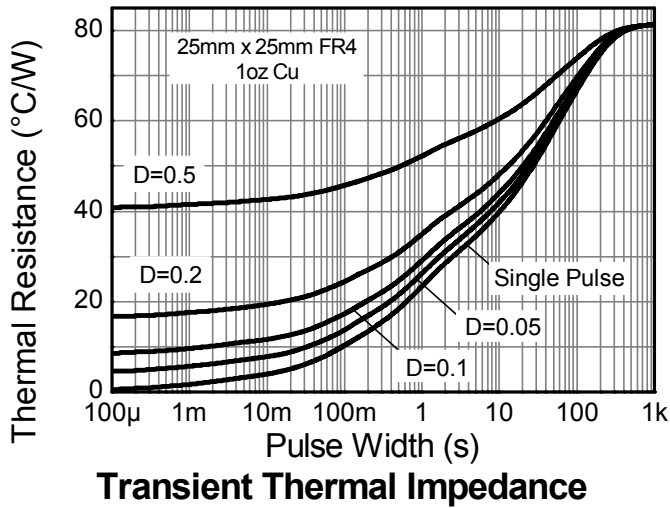
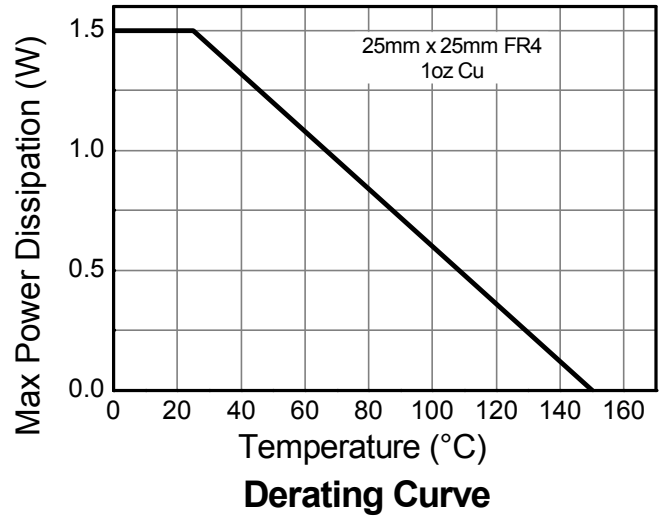
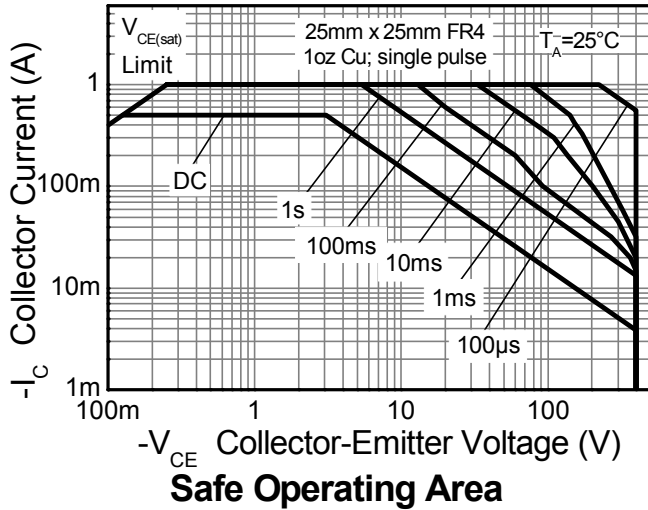
Characteristic	Symbol	Value	Unit
Power Dissipation (Note 5)	P <sub>D</sub>	1.5	W
Thermal Resistance, Junction to Ambient (Note 5)	R <sub>θJA</sub>	83	°C/W
Thermal Resistance, Junction to Leads (Note 6)	R <sub>θJL</sub>	10.4	°C/W
Operating and Storage Temperature Range	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C

### ESD Ratings (Note 7)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	8,000	V	3B
Electrostatic Discharge - Machine Model	ESD MM	400	V	C

- Notes:
5. For a device mounted with the exposed collector pad on 25mm x 25mm 1oz copper that is on a single-sided FR4 PCB; device is measured under still air conditions whilst operating in a steady-state.
  6. Thermal resistance from junction to solder-point (on the exposed collector pad).
  7. Refer to JEDEC specification JESD22-A114 and JESD22-A115.

**Thermal Characteristics and Derating information**

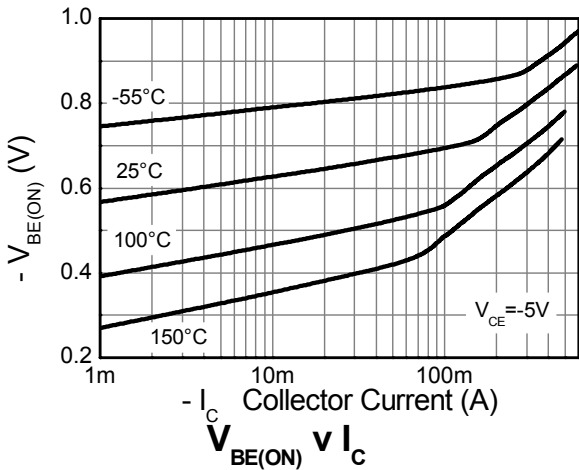
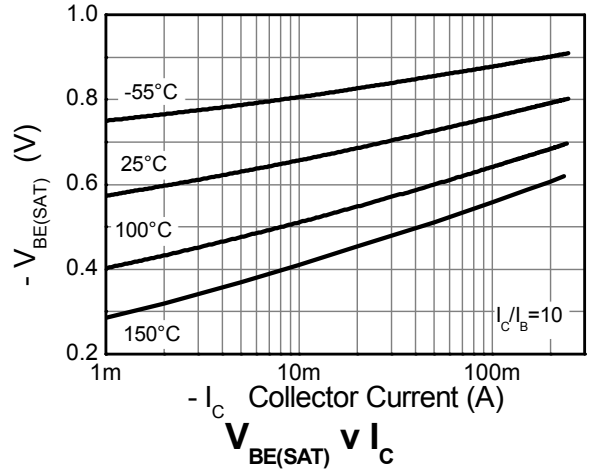
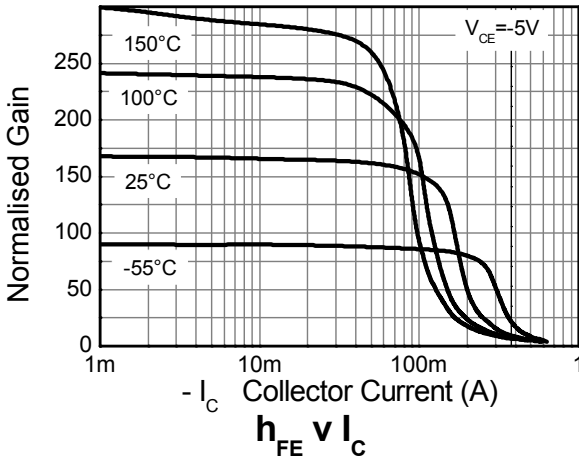
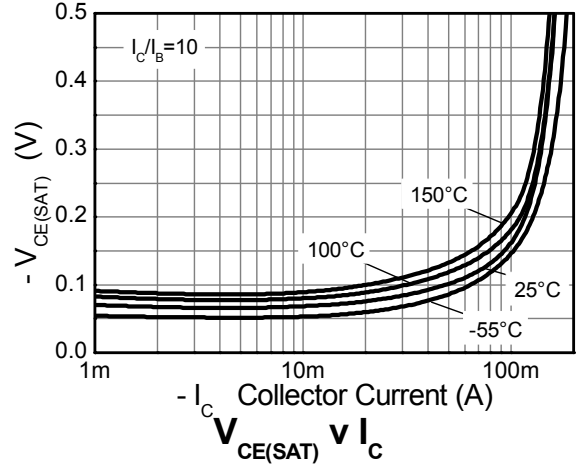
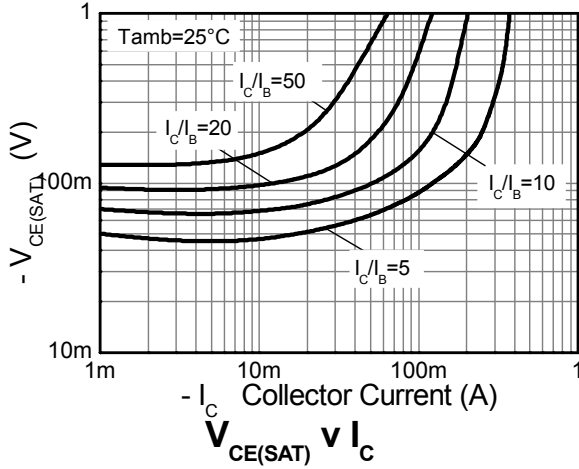


**Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	-400	-	-	V	I <sub>C</sub> = -100μA
Collector-Emitter Breakdown Voltage (Note 8)	BV <sub>CEO</sub>	-400	-	-	V	I <sub>C</sub> = -1mA
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	-7	-	-	V	I <sub>E</sub> = -100μA
Collector-Emitter Cut-off Current	I <sub>CES</sub>	-	-	-100	nA	V <sub>CE</sub> = -320V
Collector Cut-off Current	I <sub>CBO</sub>	-	-	-100	nA	V <sub>CB</sub> = -320V
Emitter Cut-off Current	I <sub>EBO</sub>	-	-	-100	nA	V <sub>EB</sub> = -6V
Static Forward Current Transfer Ratio (Note 8)	h <sub>FE</sub>	140 140	-	450 400	-	I <sub>C</sub> = -20mA, V <sub>CE</sub> = -5V I <sub>C</sub> = -100mA, V <sub>CE</sub> = -5V
Collector-Emitter saturation Voltage (Note 8)	V <sub>CE(sat)</sub>	-	-	-250 -400	mV	I <sub>C</sub> = -100mA, I <sub>B</sub> = -10mA I <sub>C</sub> = -200mA, I <sub>B</sub> = -40mA
Base-Emitter saturation Voltage (Note 8)	V <sub>BE(sat)</sub>	-	-0.75	-0.9	V	I <sub>C</sub> = -100mA, I <sub>B</sub> = -10mA
Base-Emitter Turn-On Current (Note 8)	V <sub>BE(on)</sub>	-	-	-0.8	V	I <sub>C</sub> = -200mA, V <sub>CE</sub> = -10V
Transition frequency	f <sub>T</sub>	-	75	-	MHz	I <sub>C</sub> = -50mA, V <sub>CE</sub> = -5V, f = 50MHz
Collector Output Capacitance	C <sub>obo</sub>	-	19	-	pF	V <sub>CB</sub> = -10V, I <sub>E</sub> = 0, f = 1MHz
Delay Time	t <sub>(d)</sub>	-	89	-	ns	V <sub>CC</sub> = -200V, I <sub>C</sub> = -100mA, I <sub>B1</sub> = -10mA, I <sub>B2</sub> = 20mA
Rise Time	t <sub>(r)</sub>	-	111	-	ns	
Storage Time	t <sub>(s)</sub>	-	2165	-	ns	
Fall Time	t <sub>(f)</sub>	-	185	-	ns	

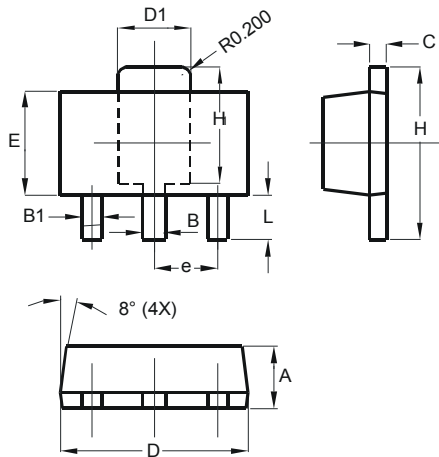
Note: 8. Measured under pulsed conditions. Pulse width ≤ 300μs. Duty cycle ≤ 2%

**Typical Electrical Characteristics** (@ $T_A = +25^\circ\text{C}$ , unless otherwise specified.)



## Package Outline Dimensions

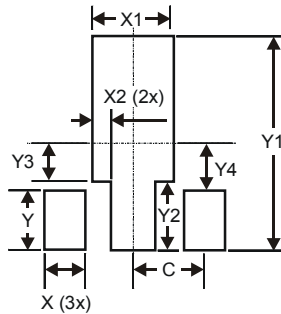
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT89		
Dim	Min	Max
A	1.40	1.60
B	0.44	0.62
B1	0.35	0.54
C	0.35	0.44
D	4.40	4.60
D1	1.62	1.83
E	2.29	2.60
e	1.50 Typ	
H	3.94	4.25
H1	2.63	2.93
L	0.89	1.20
All Dimensions in mm		

## Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for the latest version.



Dimensions	Value (in mm)
X	0.900
X1	1.733
X2	0.416
Y	1.300
Y1	4.600
Y2	1.475
Y3	0.950
Y4	1.125
C	1.500

Note: For high voltage applications, the appropriate industry sector guidelines should be considered with regards to creepage and clearance distances between device Terminals and PCB tracking.

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